OKI Semiconductor

MSM9210

32-Bit Duplex/Triplex (1/2 duty / 1/3 duty) VF Controller/Driver with Digital Dimming

This version: May 2000

Previous version: Set. 1999

GENERAL DESCRIPTION

The MSM9210 is a full CMOS controller/driver for Duplex or Triplex (1/2 duty or 1/3 duty) vacuum fluorescent display tube. It consists of a 32-segment driver multiplexed to drive up to 96 segments, and 10-bit digital dimming circuit.

MSM9210 features a selection of a master mode and a slave mode, and therefore it can be used to expand segments for the VFD driver with keyscan and A/D converter function.

MSM9210 provides an interface with a microcontroller only by three signal lines: DATA IN, CLOCK and CS.

FEATURES

Logic supply voltage (V_{DD}) : 4.5 to 5.5V
 Driver supply voltage (V_{DISP}) : 8 to 18V

 Duplex/Triplex (1/2 duty / 1/3 duty) selectable DUP/TRI=1/2 duty selectable at "H" level DUP/TRI=1/3 duty selectable at "L" level

Number of display segments
 Max. 64-segment display (during 1/2 duty mode)
 Max. 96-segment display (during 1/3 duty mode)

Master/Slave selectable
 M/S=Master mode selectable at "H" level
 M/S=Slave mode selectable at "L" level

 Interface with a microcontroller Three lines: CS, CLOCK, and DATA IN

• 32-segment driver outputs : I_{OH}=-5mA at V_{OH}=V_{DISP}-0.8V (SEG1 to 22) (can be directly connected to VFD tube and require no external resisters) : I_{OH}=-10mA at V_{OH}=V_{DISP}-0.8V (SEG23 to 32) • 3 grid pro driver outputs : I_{OL}=500µA at V_{OL}=2V (SEG1 to 32)

• 3-grid pre-driver outputs : I_{OH} =-5.0mA at V_{OH} = V_{DISP} -0.8V (require external drivers) : I_{OL} =10mA at V_{OL} =2V

• Logic outputs : I_{OH} =-200 μ A at V_{OH} = V_{DD} -0.8V I_{OL} =200 μ A at V_{OL} =0.8V

• Built-in digital dimming circuit (10-bit resolution)

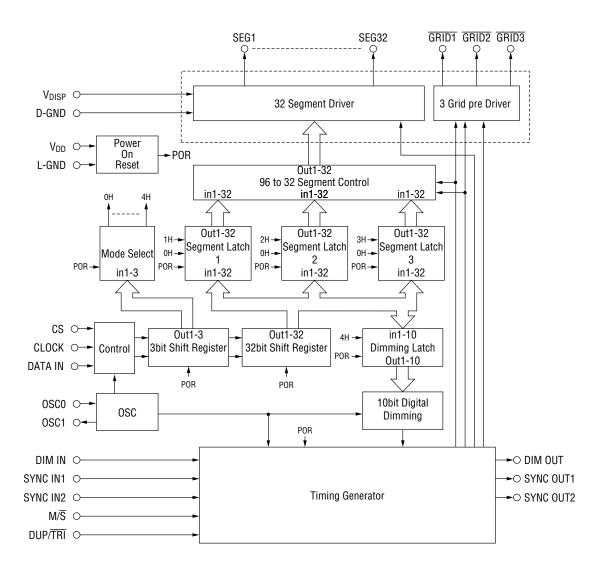
• Built-in oscillation circuit (external R and C)

• Built-in Power-On-Reset circuit

Package options:

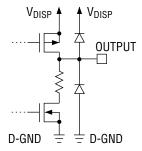
56-pin plastic QFP (QFP56-P-910-0.65-2K) Product name: MSM9210GS-2K 64-pin plastic QFP (QFP64-P-1414-0.80-BK) Product name: MSM9210GS-BK

BLOCK DIAGRAM

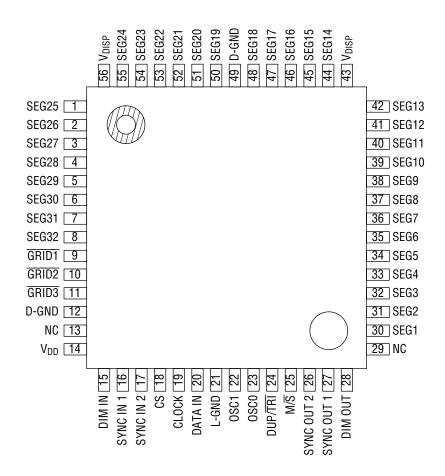


INPUT AND OUTPUT CONFIGURATION

Schematic Diagram of Driver Output Circuit

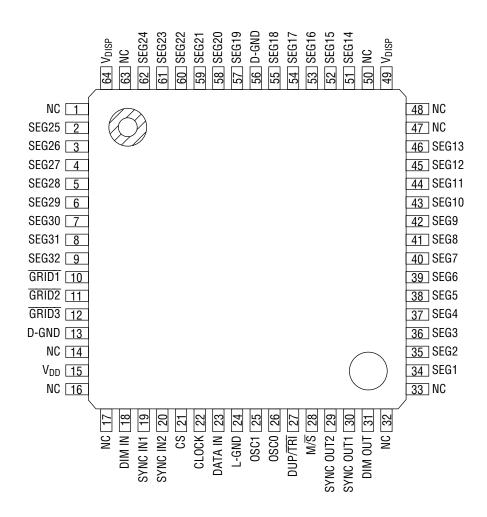


PIN CONFIGURATION (TOP VIEW)



NC: No connection

56-pin Plastic QFP



NC: No connection

64-pin Plastic QFP

PIN DESCRIPTIONS

Console al	Р	in	T	Description
Symbol	QFP56	QFP64	Туре	Description
Valor	43,56	49,64		Power supply pins for VFD driver circuit.
V_{DISP}	45,50	43,04		43 pin and 56 pin should be connected externally.
V_{DD}	14	15	_	Power supply pin for logic drive.
D-GND	12, 49	13, 56	_	D-GND is ground pin for the VFD driver circuit. L-GND is ground
L-GND	21	24	_	pin for the logic circuit. 12pin, 21pin and 49pin should be connected externally.
SEG1 to 22	30 to 42, 44 to 48, 50 to 53	34 to 46, 51 to 55, 57 to 60	0	Segment (anode) signal output pins for a VFD tube. These pins can be directly connected to the VFD tube. External circuit is not required. IOH≤−5 mA
SEG23 to 32	1 to 8, 54, 55	2 to 9, 61, 62	0	Segment (anode) signal output pins for a VFD tube. These pins can be directly connected to the VFD tube. External circuit is not required. IOH≤−10 mA
GRID1 to 3	9, 10, 11	10, 11, 12	0	Inverted Grid signal output pins. For pre-driver, the external circuit is required. IOL≤10 mA
CS	18	21	I	Chip select input pin. Data is not transferred when CS is set to a Low level.
CLOCK	19	22	I	Shift clock input pin. Serial data shifts at the rising edge of the CLOCK.
DATA IN	20	23	I	Serial data input pin (positive logic). Data is input to the shift register at the rising edge of the CLOCK signal
DUP/TRI	24	27	I	Duplex/Triplex operation select input pin. Duplex (1/2 duty) operation is selected when this pin is set to V_{DD} . Triplex (1/3 duty) operation is selected when this pin is set to L-GND.
M/S	25	28	I	Master/Slave mode select input pin. Master mode is selected when this pin is set to V _{DD} . Slave mode is selected when this pin is set to L-GND.
DIM IN	15	18	I	Dimming pulse input. When the slave mode is selected, the pulse width of the all segment output are controlled by a input pulse width of DIM IN. Connect this pin to the master side DIM OUT pin at the slave mode. When the master mode is selected, the input level of this pin is ignored and the pulse width of the all grids and segment outputs are controlled by a built-in 10-bit dimming circuit. Connect this pin to V _{DD} or L-GND at the master mode.

Sumb al	Р	in	Tyma	Description
Symbol	QFP56	QFP64	Туре	Description
SYNC IN 1, 2	16, 17	19, 20	I	Synchronous signal input. When the slave mode is selected, connect these pins to the master side SYNC OUT 1, and 2 pins. When the master mode is selected, the input level of these pins are ignored. Connect these pins to V _{DD} or L-GND at the master mode.
DIM OUT	28	31	0	Dimming pulse output. Connect this pin to the slave side DIM IN pin.
SYNC OUT 1, 2	26, 27	29, 30	0	Synchronous signal output. Connect these pins to the slave side SYNC IN 1, and 2 pins.
OSC0	23	26	I	RC oscillator connecting pins. Oscillation frequency depends on R C
0801	22	25	0	display tubes to be used. For details, refer to ELECTRICAL CHARACTERISTICS.

ABSOLUTE MAXIMUM RATING

Parameter	Symbol	Condition	Ratings	Unit
Driver Supply Voltage	V_{DISP}	_	-0.3 to +20	V
Logic Supply Voltage	V_{DD}	_	-0.3 to +6.5	V
Input Voltage	V _{IN}	_	-0.3 to V _{DD} +0.3	V
Power Dissipation	P _D	Ta≥25°C	260	mW
Storage Temperature	T _{STG}	_	-55 to +150	°C
	I ₀₁	SEG1 to 22	-10.0 to +2.0	mA
Output Current	I ₀₂	SEG23 to 32	-20.0 to +2.0	mA
Output Current	I ₀₃	GRID1 to 3	-10.0 to +20.0	mA
	I ₀₄	DIM OUT, SYNC OUT1, SYNC OUT2	-2.0 to +2.0	mA

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Driver Supply Voltage	V _{DISP}	_	8.0	13.0	18.0	V
Logic Supply Voltage	V_{DD}	_	4.5	5.0	5.5	V
High Level Input Voltage	V _{IH}	All inputs except OSCO	0.8V _{DD}	_	_	V
Low Level Input Voltage	V _{IL}	All inputs except OSCO	_	_	0.2V _{DD}	V
Clock Frequency	f _C	_	_	_	1.0	MHz
Operating Temperature	T _{OP}	_	-40	_	+85	°C

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When a 1/2 duty VFD tube is used

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Oscillation Frequency	fosc	R=8.2K Ω ±5%, C=22pF±5%	1.0	1.5	2.0	MHz
Frame Frequency	f _{FR}	R=8.2K Ω ±5%, C=22pF±5%	122	183	244	Hz

When a 1/3 duty VFD tube is used

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Oscillation Frequency	fosc	$R=6.2K\Omega\pm5\%$, $C=22pF\pm5\%$	1.5	2.25	3.0	MHz
Frame Frequency	f _{FR}	R=6.2K Ω ±5%, C=22pF±5%	122	183	244	Hz

ELECTRICAL CHARACTERISTICS

DC Characteristics

 $Ta=-40 \text{ to } +85^{\circ}\text{C}, V_{DISP} = 8.0 \text{ to } 18.0\text{V}, V_{DD}=4.5 \text{ to } 5.5\text{V}$

Parameter	Symbol	Applied pin	Con	dition	Min.	Max.	Unit
High Level Input Voltage	V_{IH}	*1)		_	0.8V _{DD}	_	V
Low Level Input Voltage	V _{IL}	*1)		_	_	$0.2V_{DD}$	V
High Level Input Current	I _{IH}	*1)	V _{IH}	$=V_{DD}$	-1.0	+1.0	μΑ
Low Level Input Current	I _{IL}	*1)	V _{IL} :	=GND	-1.0	+1.0	μΑ
	V _{OH1}	SEG1-22		I _{OH1} =–5mA	V _{DISP} -0.8	_	V
High Lavel Output Voltage	V_{OH2}	SEG23-32	V _{DISP} =9.5V	I _{OH2} =-10mA	V _{DISP} -0.8	_	V
High Level Output Voltage	V_{OH3}	GRID1-3		I _{OH3} =–5mA	V _{DISP} -0.8	_	V
	V_{OH4}	*2)	V _{DD} =4.5V	Ι _{0H4} =-200μΑ	V _{DD} -0.8	_	V
	V _{OL1}	SEG1-22		I _{0L1} =500μA	_	2.0	V
Low Lovel Output Voltage	V_{0L2}	SEG23-32	V _{DISP} =9.5V	I _{0L2} =500μA	_	2.0	V
Low Level Output Voltage	V_{OL3}	GRID1-3		I _{OL3} =10mA	_	2.0	V
	V_{0L4}	*2)	V _{DD} =4.5V	I _{0L4} =200μA	_	0.8	V
Cupply Current	I _{DISP}	V_{DISP}	f _{OSC} =3.0N	/IHz, no load	_	100	μΑ
Supply Current	I_{DD}	V_{DD}	f _{OSC} =3.0N	/IHz, no load	_	5.0	mA

^{*1)} CS, CLOCK, DATA IN, DIM IN, SYNC IN 1, SYNC IN 2, M/\overline{S} , DUP/\overline{TRI}

^{*2)} DIM OUT, SYNC OUT 1, SYNC OUT 2

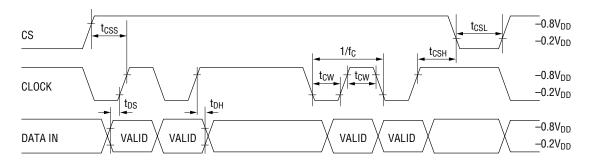
AC Characteristics

 $Ta=-40 \text{ to } +85^{\circ}\text{C}, V_{DISP} = 8.0 \text{ to } 18.0\text{V}, V_{DD}=4.5 \text{ to } 5.5\text{V}$

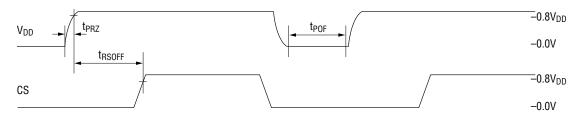
Parameter	Symbol	Con	dition	Min.	Max.	Unit
Clock Frequency	f _C		_	_	1.0	MHz
Clock Pulse Width	t _{CW}		_	400	_	ns
Data Setup Time	t _{DS}			400	_	ns
Data Hold Time	t _{DH}			400	_	ns
CS Off Time	t _{CSL}		_	20	_	μs
CS Setup Time	+			400		200
(CS-Clock)	t _{CSS}			400	_	ns
CS Hold Time				400		20
(Clock-CS)	t _{CSH}			400	_	ns
CS Wait Time	t _{RSOFF}		_	400	_	μs
Output Clay Data Tima	t _R	C 100pE	t _R =20% to 80%		2.0	μs
Output Slew Rate Time	t _F	C _L =100pF			2.0	μs
V _{DD} Rise Time	t _{PRZ}	Mounte	d in a unit		100	μs
V _{DD} Off Time	t _{POF}	Mounted in a	unit, V _{DD} =0.0V	5.0	_	ms

TIMING DIAGRAM

Data Input Timing



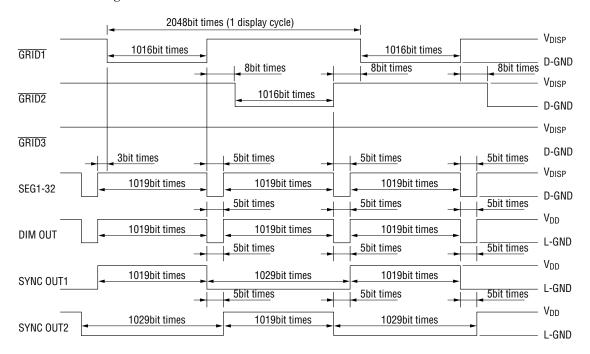
Reset Timing



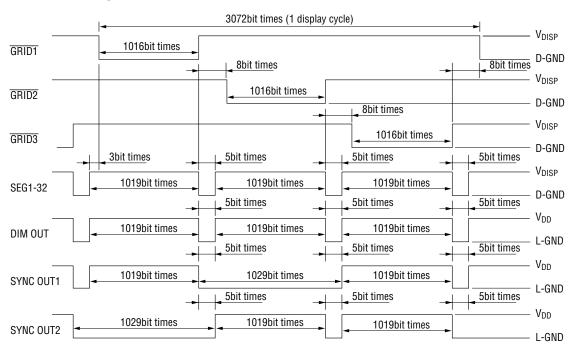
Driver Output Timing



● Output Timing (Duplex Operation) *1bit time=4/f_{OSC} (The dimming data is 1016/1024 at the master mode)



● Output Timing (Triplex Operation) *1bit time=4/f_{OSC} (The dimming data is 1016/1024 at the master mode)



FUNCTIONAL DESCRIPTION

Power-on Reset

When power is turned on, MSM9210 is initialized by the internal power-on reset circuit.

The status of the internal circuit after initialization is as follows:

- The contents of the shift registers and latches are set to "0".
- The digital dimming duty cycle is set to "0".
- All segment outputs are set to Low level.
- All grid outputs are set to High level.

Data Transfer Method

Data can be transferred between the rising edge and the next falling edge of chip select input. The mode data, segment data and dimming data are written by a serial transfer method. The serial data is input to the shift register at the rising edge of a shift clock pulse.

The mode data (M0 to M2) must be transferred after the segment data and dimming data succeedingly.

When the chip select input falls, an internal LOAD signal is automatically generated and data is loaded to the latches.

Function Mode

Function mode is selected by the mode data (M0 to M2). The relation between function mode and mode data is as follows:

FUNCTION MODE	OPERATING MODE	FUNC	FUNCTION D			
FUNCTION MODE	OPERATING MODE	MO	M1	M2		
0	Segment Data for GRID1-3 Input	0	0	0		
1	Segment Data for GRID1 Input	1	0	0		
2	Segment Data for GRID2 Input	0	1	0		
3	Segment Data for GRID3 Input	1	1	0		
4	Digital Dimming Data Input	0	0	1		

Segment Data Input [Function Mode: 0 to 3]

- MSM9210 receives the segment data when function mode 0 to 3 are selected.
- The same segment data is transferred to the 3 segment data latches corresponding to GRID 1 to 3 at the same time when the function mode 0 is selected.
- The segment data is transferred to only one segment data latch corresponding to the specified GRID when the function mode is 1, 2 or 3 is selected.
- Segment output (SEG1 to 32) becomes High level (lightning) when the segment data (S1 to S32) is set to "1".

[Data Format]

Input Data : 35 bits Segment Data : 32 bits Mode Data : 3 bits

Bit	1	2	3	4		29	30	31	32	33	34	35
Input Data	S1	S2	S3	S4		S29	S30	S31	S32	M0	M1	M2
	•			Segme	ent Data (3	32bits)			-	⊸ M	ode Da (3bits)	

[Bit correspondence between segment output and segment data]

SEG n	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
Segment data	S1	S2	S3	S4	S5	S6	S7	S8	S9	S10	S11	S12	S13	S14	S15	S16
SEG n	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32
Segment data	S17	S18	S19	S20	S21	S22	S23	S24	S25	S26	S27	S28	S29	S30	S31	S32

Digital Dimming Data Input [Function Mode: 4]

- MSM9210 receives the digital dimming data when function mode 4 is selected.
- The output duty changes in the range of 0/1024 (0%) to 1016/1024 (99.2%) for each grid.
- The 10-bit digital dimming data is input from LSB.

[Data Format]

Input Data : 13 bits Digital Dimming Data: 10 bits Mode Data : 3 bits

	Bit	1	2	3	4	5	6	7	8	9	10	11	12	13
	Input Data	D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	M0	M1	M2
										MSB		ode Da (3bits)	,	

(LSB)	B) Dimming Data								(MSB)	Duty Cycle
D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	Duty Cycle
0	0	0	0	0	0	0	0	0	0	0/1024
1	0	0	0	0	0	0	0	0	0	1/1024
1	1	1	0	1	1	1	1	1	1	1015/1024
0	0	0	1	1	1	1	1	1	1	1016/1024
1	0	0	1	1	1	1	1	1	1	1016/1024
1	1	1	1	1	1	1	1	1	1	1016/1024

Master Mode

Master Mode is selected when M/\overline{S} pin is set at High level. The master mode operation is as follows:

- The input levels of DIM IN, SYNC IN1 and SYNC IN2 are ignored, and these pins should be connected to L-GND or V_{DD}.
- The pulse width of GRID1 to 3 and SEG1 to 32 are controlled by the internal digital dimming circuit.
- The segment Latch1 to 3 corresponding to GRID1 to 3 are selected by the internal timing generator.

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Slave Mode

Slave Mode is selected when M/\overline{S} pin is set at Low level. The slave mode operation is as follows:

- The internal dimming circuit is ignored.
- The pulse width of SEG1 to 32 are controlled by the pulse width of DIM IN signal.
- The segment Latch1 to 3 corresponding to GRID1 to 3 are selected by SYNC IN1 and SYNC IN2 signals.
- The output levels of GRID1 to 3 are set at High level. The output levels of DIM OUT, SYNC OUT1 and SYNC OUT2 are set at Low level.

[Correspondence between SYNC IN1, 2 and Segment Latch1 to 3] [Correspondence between DIM IN and SEG1 to 32]

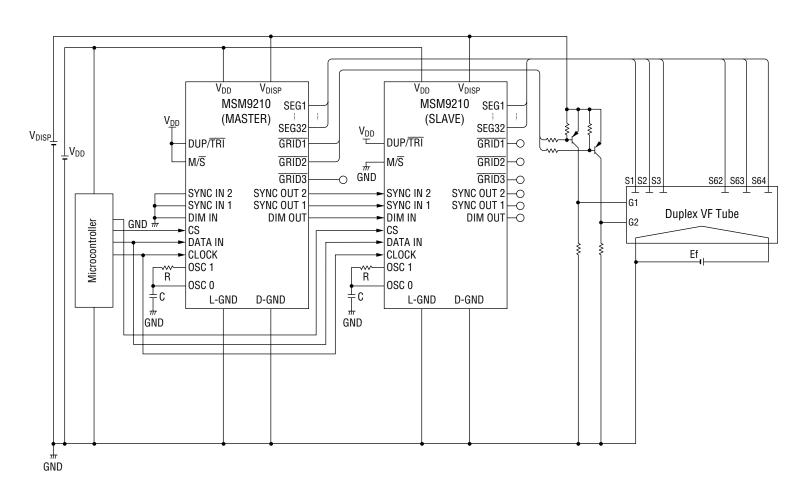
SYNC IN 1	SYNC IN 2	Segment Latch	GRID
0	0	No	No
1	0	Latch1	GRID1
0	1	Latch2	GRID2
1	1	Latch3	GRID3

DIM IN	SEG1 to 32			
0	Low			
1	High			

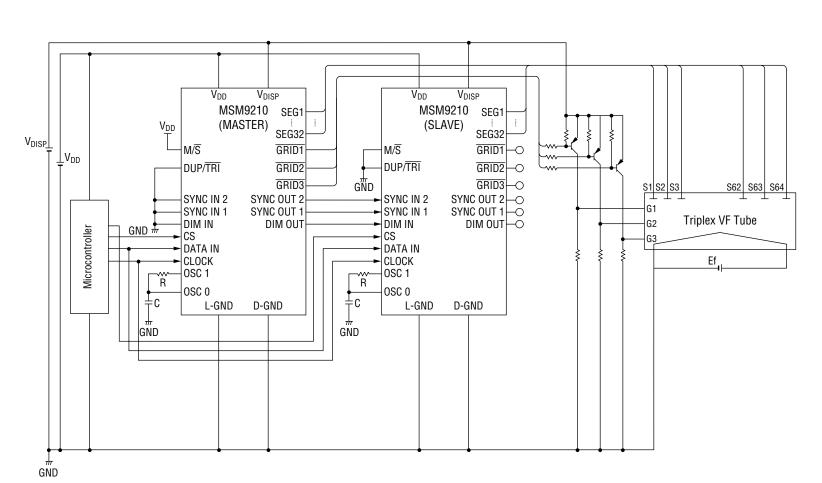
Note: Low: Lights OFF High: Lights ON

APPLICATION CIRCUITS

1. Circuit for the duplex VFD tube with 128 segments (2 Grid \times 64 Anode)

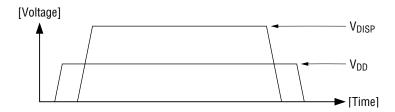


Ы Circuit for the triplex VFD tube with 192 segments (3 Grid \times 64 Anode)



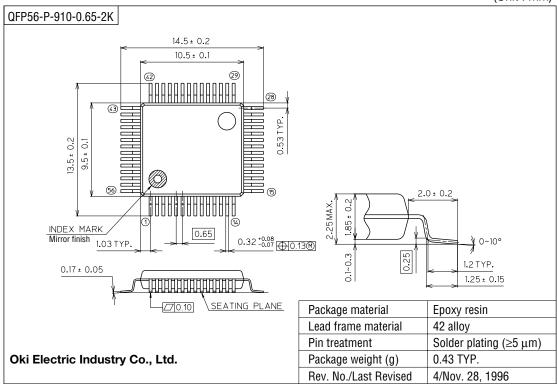
NOTES ON TURNING POWER ON/OFF

- Connect L-GND and D-GND externally to be an equal potential voltage.
- To avoid wrong operations, turn on the driver power supply after turning on the logic power supply. Conversely, turn off the logic power supply after tuning off the driver power supply.



PACKAGE DIMENSIONS

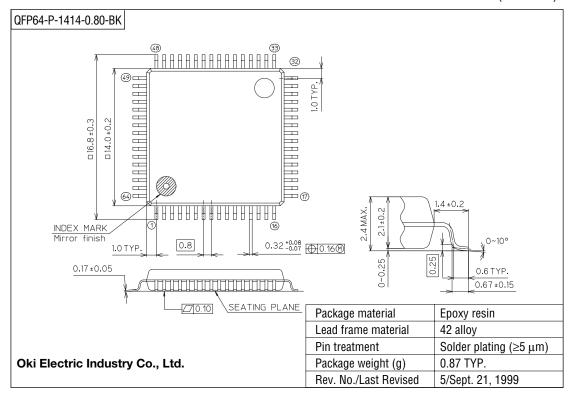
(Unit: mm)



Notes for Mounting the Surface Mount Type Package

The SOP, QFP, TSOP, SOJ, QFJ (PLCC), SHP and BGA are surface mount type packages, which are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

(Unit: mm)



Notes for Mounting the Surface Mount Type Package

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